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FIG. 1

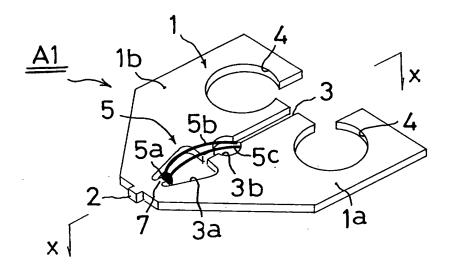


FIG. 2

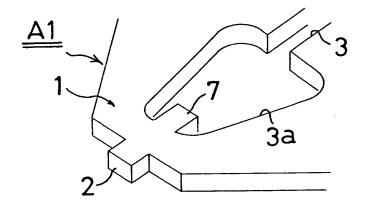
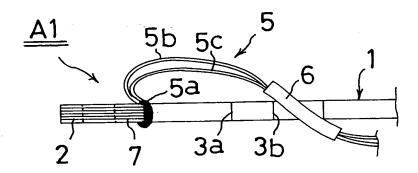


FIG. 3



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FIG. 4

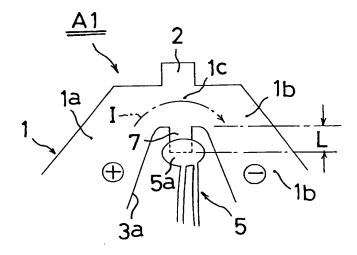


FIG. 5

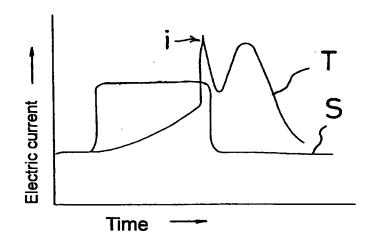
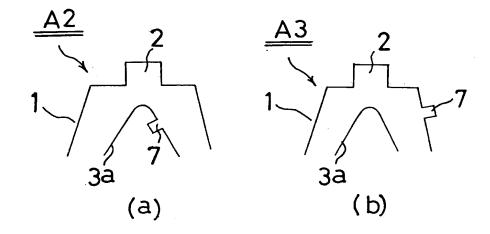


FIG. 6



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FIG. 7

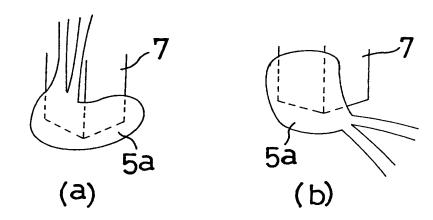


FIG. 8

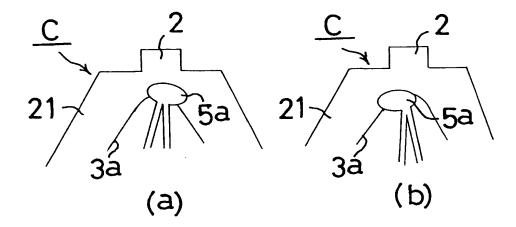
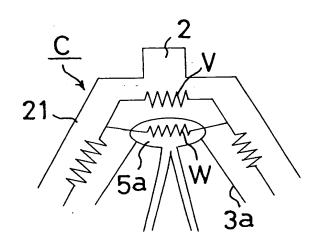


FIG. 9



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FIG. 10

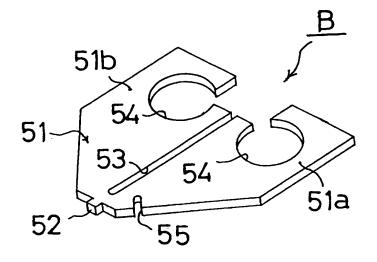


FIG. 11

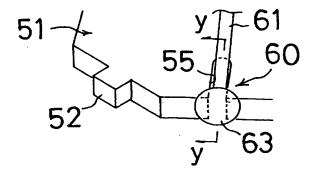
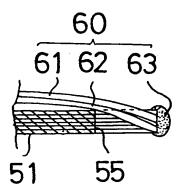


FIG. 12



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FIG. 13

